



Polyimide Coverlay

Polyimide Coverlay is made of polyimide film coated by modified stage-B acrylic adhesive on one side with protection release film or paper. Polyimide Coverlay is widely used in protection of FPCB. (Epoxy also available)

Characters:

- * Excellent dielectric performance, high bondability and good dimension stability
- * Low fluidity and good processability.
- * Supplied with different sizes and colours (yellow, black, white, etc.)

NOTE: Please contact us for customized polyimide stiffeners and bondplys

Spec.:

Models AD/PI/AD (AD=adhesive; PI=polyimide film)	Unit	PIC-5A 12.5/12.5/0	PIC-10A 25/25/0	PIC-20AS 25/50/0	PIC-30AS 25/75/0
Typical Thickness	mm±10%	0.025	0.05	0.075	0.10
Film Thickness	mm	0.0125(0.5mil)	0.025(1 mil)	0.05(2mil)	0.075(3mil)
Adhesive thickness	mm	0.0125	0.025	0.025	0.025
Nominal Weight(Film and adhesive)	g/m ² ±10%	35	70	105	140
Supply Size and Packing	Standard roll: 50m ² per roll, width: 500mm Carton after winded up into log roll and sealed by plastic film bag, Core ID: 3"				

Note: both customization and epoxy counterpart can also be available.

Typical Properties (The follows are just examples not read as guaranteed values)

Items	Unit	Test Method	Typical datas
1. Peel Strength -As normal conditions -After soldering	N/mm--width	IPC-TM-650-2.4.9	1.05 1.05
2. Dimensional Stability	%	IPC-TM-650-2.2.4A	0.10
3. Adhesive Flow max.(overflow)	um	IPC-TM-650-2.3.17.1	<130
4. Volatile Content	%	IPC-TM-650-2.3.37	≤3.0
5. Soldering resistance	288℃/10sec.	IPC-TM-650-2.4.13	Pass
6. Moisture Absorption	%	IPC-TM-650-2.6.2	≤4.0
7. Dielectric strength	KV/mm	ASTM-D-149	≥50
8. Chemical resistance	%	IPC-TM-650-2.3.2	≥80
9. Dielectric constant	MHZ	IPC-TM-650-2.5.5.3	≤4.0
10. Dissipation factor	-----	IPC-TM-650-2.5.5.3	≤0.04
11. Volume resistivity	MΩ-cm	IPC-TM-650-2.5.17	10 ⁸
12. Surface resistivity	MΩ	IPC-TM-650-2.5.17	10 ⁶

Storage:

The product is packed in reinforced carton and sealed in plastic film bag. Please keep dry and in room temperature. Shelf life is 12 months.

Application:

Polyimide Coverlay is mainly used in protection of flexible printed circuit board and other relevant fields.

Recommendation of work condition: Pressure: 15 ~ 20 kgf/cm²; Temperature: 165 ~ 175℃; Time: 45 ~ 60min.

Note: 1. All of above information is based on our best knowledge, not read as guarantees. Right reserved for corrections.
2. Please contact us if customization requirements.

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